



KE-1300T/CAT-1300L-2

Shin-Etsu Silicones of America, Inc.
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Product Description

Shin-Etsu's KE-1300T/CAT-1300L-2 is a high strength, high modulus mold making/potting compound of the addition polymerization type with an extended pot life. KE-1300T/CAT-1300L-2 exhibits excellent tear resistance, low shrinkage and easy release making it an excellent mold making material.

Product Features

- High tensile strength
- Excellent tear resistance
- Low shrinkage
- Easy release

Typical Applications

- Mold making applications requiring high strength molds

Typical Properties

Type	Mold Making
Cure Type	Addition
One/Two Component	Two
Color	Translucent
Density @ 23C (g/cm ³)	1.07
Viscosity Base (Pa·s)	75.00
Catalyst	CAT-1300L-2
Mix Ratio by weight	100:10
Cure Conditions	72hr @ 23C
Working Time	16 Hours
Shore A Hardness	40
Tensile Strength (MPa)	5.90
Tear Strength (kN/m)	22.00000
% Elongation	340
Usable Temperature Range (C)	-40 to +175

Note: Values are not for specification purposes.

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